Solder paste NP303-WS4070-T4

GENMA
EUROPE

Product description

GENMA solder paste – our NP303-WS4070-T4 solder paste with water soluble flux. It convinces with its outstanding printability, highly precise contours, long open time, and consistent adhesiveness in the pick-and-place process. Its extremely good wetting properties, also on difficult surfaces, produce perfect soldering joints on BGAs. Hardly any voids in the solder connections. Cleaning of flux residues with water after soldering is required. The solder paste can be soldered under air or nitrogen reflow.

Technical properties

	Specific value	Testing method
Alloy	Sn 96,5 / Ag 3,0 / Cu 0,5 / SAC305	
Melting temperature range	217 - 221	IEC61189-11
Powder size (μm)	22 - 38, type 4	IPC-TM-650-2.2.14.2
Viscosity (Pa · s)	200 ± 30	IPC-TM-650-2.4.34.3
Flux content (wt %)	12 ± 0,5	IPC-TM-650-2.3.34.1
Halide content (wt %)	≤ 0,05	IPC-TM-650-2.3.35
Migration test	No migration	IPC-TM-650-2.6.14.1
Copper mirror test	No corrosion	IPC-TM-650-2.3.32
Packaging	Jar (0,5 kg) Semco cartridge (0,65 kg, 1,2 kg)	
Transport	Keep cool	
Tempering the solder paste	Set to room temperature before opening to avoid condensation.	
Recommended printing speed (mm/s)	20 - 80	
Recommended temperature during print (°C)	25 ± 3	
Recommended relative humidity in % during print	50 ± 20	

Compliance

Conform with RoHS-Regulation 2011/65/EU

Contains no substances more than threshold (0,1%) according to REACH legislation EG Nr. 1907/2006 (SVHC-list - dated 27.06.2018)

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